



BAT46WH-Q

Schottky barrier diode

20 March 2023

Product data sheet

1. General description

Planar Schottky barrier diode with an integrated guard ring for stress protection, encapsulated in a small and flat lead SOD123F Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Low forward voltage
- Reverse voltage $V_R \leq 100$ V
- Small and flat lead SMD plastic package
- Low capacitance
- Qualified according to AEC-Q101 and recommended for use in automotive applications

3. Applications

- High-speed switching
- Line termination
- Voltage clamping
- Reverse polarity protection

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_R	reverse voltage		-	-	100	V
V_F	forward voltage	$I_F = 250$ mA; pulsed; $t_p \leq 300$ μ s; $\delta \leq 0.02$; $T_{amb} = 25$ °C	-	710	850	mV
I_R	reverse current	$V_R = 75$ V; $t_p \leq 300$ μ s; $\delta \leq 0.02$; pulsed; $T_{amb} = 25$ °C	-	1	4	μ A

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]	 SOD123F	 K A aaa-003679
2	A	anode		

[1] The marking bar indicates the cathode.

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BAT46WH-Q	SOD123F	plastic, surface-mounted package; 2 leads; 2.6 mm x 1.6 mm x 1.1 mm body	SOD123F

7. Marking

Table 4. Marking codes

Type number	Marking code
BAT46WH-Q	DB

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_R	reverse voltage			-	100	V
I_F	forward current			-	250	mA
I_{FSM}	non-repetitive peak forward current	$t_p < 10$ ms; square wave; $T_{j(\text{init})} = 25$ °C		-	2.5	A
P_{tot}	total power dissipation	$T_{\text{amb}} \leq 25$ °C	[1]	-	440	mW
			[2]	-	780	mW
T_j	junction temperature			-	150	°C
T_{amb}	ambient temperature			-55	150	°C
T_{stg}	storage temperature			-65	150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for cathode 1 cm².

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{\text{th}(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	-	285	K/W
			[2]	-	-	160	K/W
$R_{\text{th}(j-sp)}$	thermal resistance from junction to solder point		[3]	-	-	25	K/W

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

[3] Soldering point of cathode tab.

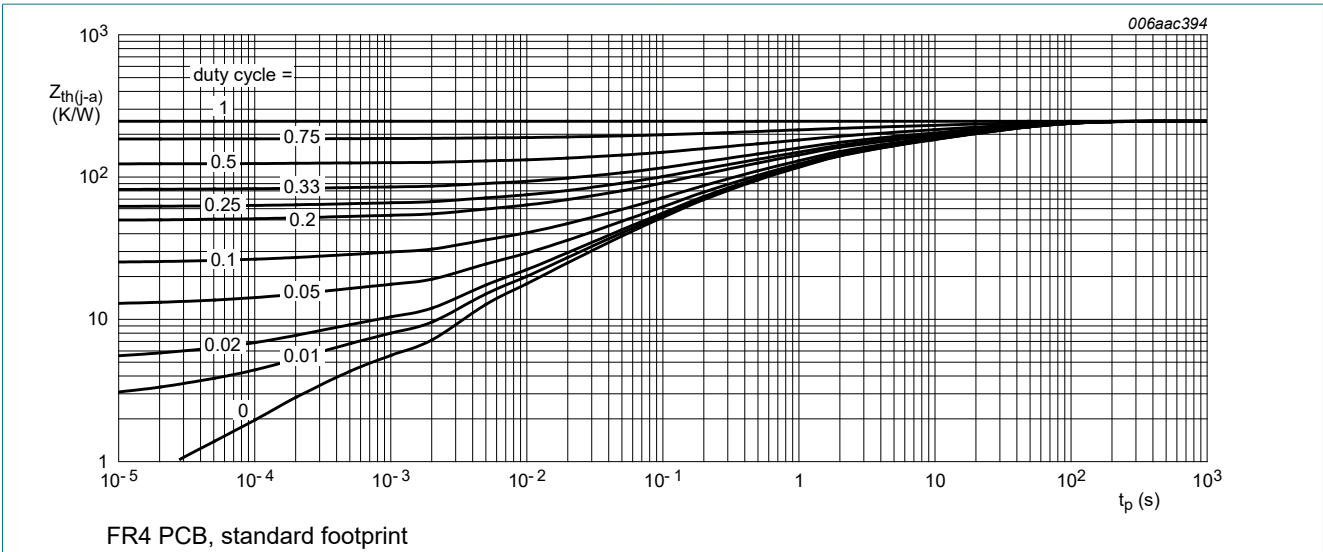


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

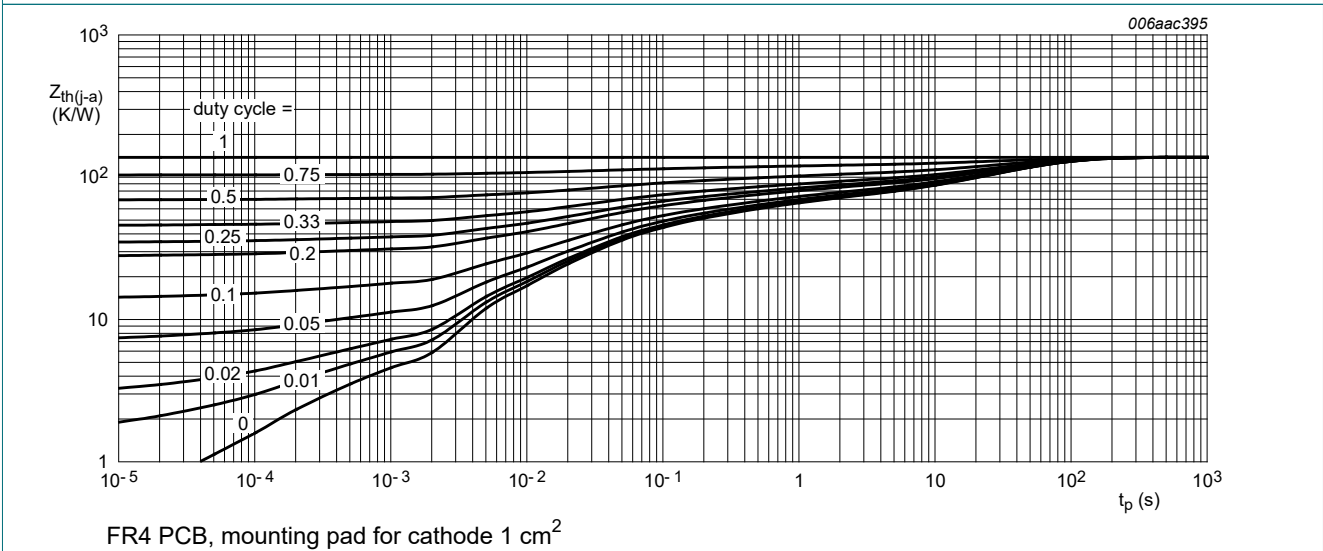
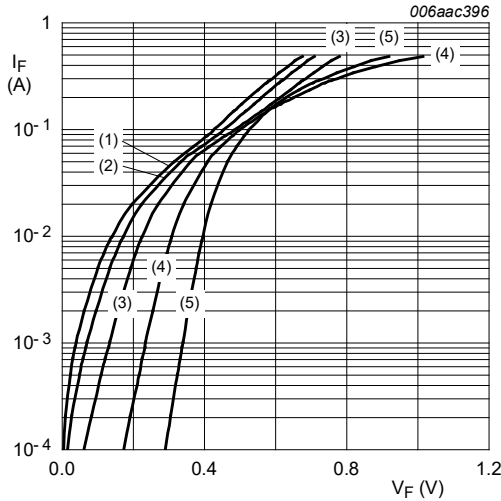


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

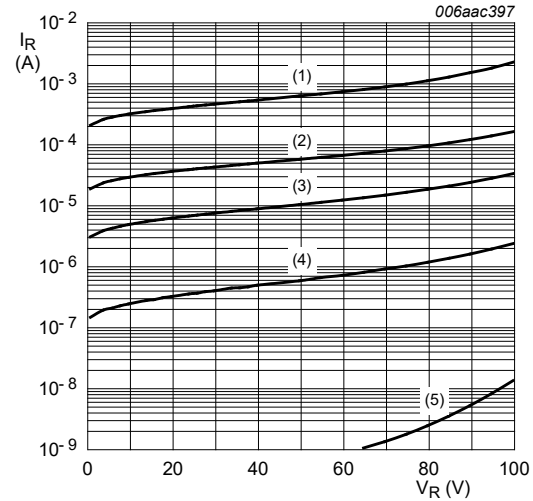
Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_F	forward voltage	$I_F = 0.1 \text{ mA}$; pulsed; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$	-	175	200	mV
		$I_F = 10 \text{ mA}$; pulsed; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$	-	315	350	mV
		$I_F = 10 \text{ mA}$; pulsed; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; $T_J = -40 \text{ }^\circ\text{C}$	-	-	470	mV
		$I_F = 50 \text{ mA}$; pulsed; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$	-	415	475	mV
		$I_F = 50 \text{ mA}$; pulsed; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; $T_J = -40 \text{ }^\circ\text{C}$	-	-	560	mV
		$I_F = 250 \text{ mA}$; pulsed; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$	-	710	850	mV
I_R	reverse current	$V_R = 1.5 \text{ V}$; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; pulsed; $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$	-	0.2	0.5	μA
		$V_R = 1.5 \text{ V}$; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; pulsed; $T_J = 60 \text{ }^\circ\text{C}$	-	-	12	μA
		$V_R = 10 \text{ V}$; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; pulsed; $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$	-	0.3	0.8	μA
		$V_R = 10 \text{ V}$; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; pulsed; $T_J = 60 \text{ }^\circ\text{C}$	-	-	20	μA
		$V_R = 50 \text{ V}$; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; pulsed; $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$	-	0.7	2	μA
		$V_R = 50 \text{ V}$; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; pulsed; $T_J = 60 \text{ }^\circ\text{C}$	-	-	44	μA
		$V_R = 75 \text{ V}$; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; pulsed; $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$	-	1	4	μA
		$V_R = 75 \text{ V}$; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; pulsed; $T_J = 60 \text{ }^\circ\text{C}$	-	-	80	μA
		$V_R = 100 \text{ V}$; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; pulsed; $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$	-	2	9	μA
		$V_R = 100 \text{ V}$; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; pulsed; $T_J = 60 \text{ }^\circ\text{C}$	-	-	120	μA
		$V_R = 100 \text{ V}$; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; pulsed; $T_J = 85 \text{ }^\circ\text{C}$	-	-	600	μA
C_d	diode capacitance	$V_R = 0 \text{ V}$; $f = 1 \text{ MHz}$; $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$	-	-	39	pF
		$V_R = 1 \text{ V}$; $f = 1 \text{ MHz}$; $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$	-	-	21	pF
t_{rr}	reverse recovery time	$I_F = 10 \text{ mA}$; $I_R = 10 \text{ mA}$; $I_{R(\text{meas})} = 1 \text{ mA}$; $R_L = 100 \Omega$; $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$	-	5.9	-	ns



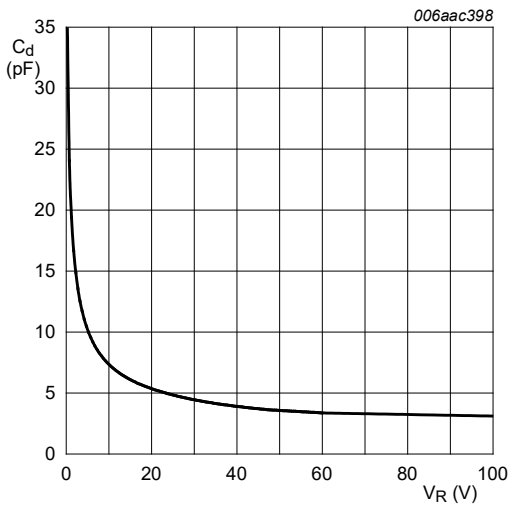
- (1) $T_{amb} = 150^\circ\text{C}$
- (2) $T_{amb} = 125^\circ\text{C}$
- (3) $T_{amb} = 85^\circ\text{C}$
- (4) $T_{amb} = 25^\circ\text{C}$
- (5) $T_{amb} = -40^\circ\text{C}$

Fig. 3. Forward current as a function of forward voltage; typical values



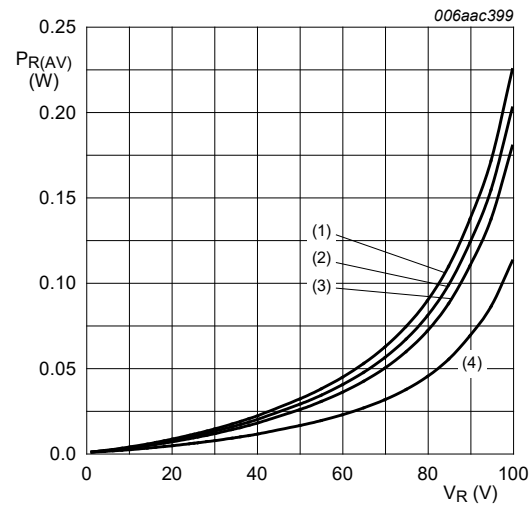
- (1) $T_{amb} = 125^\circ\text{C}$
- (2) $T_{amb} = 85^\circ\text{C}$
- (3) $T_{amb} = 60^\circ\text{C}$
- (4) $T_{amb} = 25^\circ\text{C}$
- (5) $T_{amb} = -40^\circ\text{C}$

Fig. 4. Reverse current as a function of reverse voltage; typical values



$f = 1\text{ MHz}$; $T_{amb} = 25^\circ\text{C}$

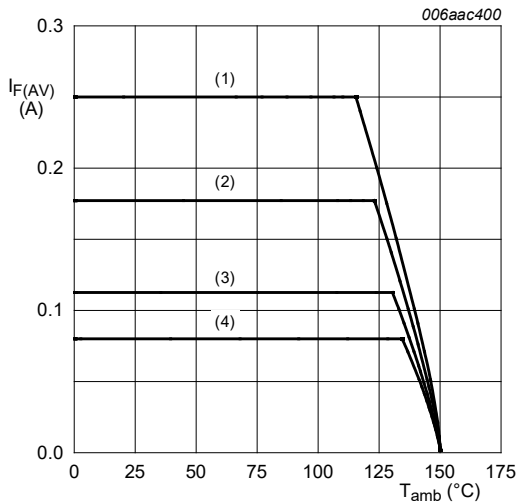
Fig. 5. Diode capacitance as a function of reverse voltage; typical values



$T_j = 125^\circ\text{C}$

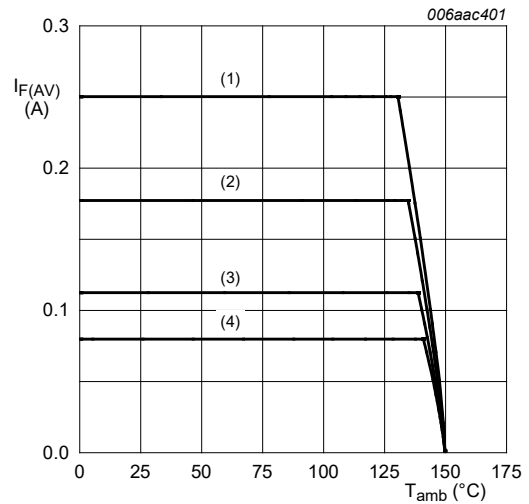
- (1) $\delta = 1$
- (2) $\delta = 0.9$
- (3) $\delta = 0.8$
- (4) $\delta = 0.5$

Fig. 6. Average reverse power dissipation as a function of reverse voltage; typical values



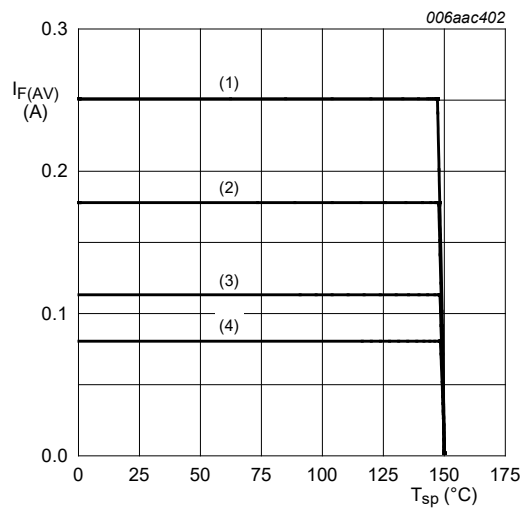
FR4 PCB, standard footprint
 $T_j = 150\text{ °C}$
 (1) $\delta = 1$; DC
 (2) $\delta = 0.5$; $f = 20\text{ kHz}$
 (3) $\delta = 0.2$; $f = 20\text{ kHz}$
 (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig. 7. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm^2
 $T_j = 150\text{ °C}$
 (1) $\delta = 1$; DC
 (2) $\delta = 0.5$; $f = 20\text{ kHz}$
 (3) $\delta = 0.2$; $f = 20\text{ kHz}$
 (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig. 8. Average forward current as a function of ambient temperature; typical values



$T_j = 150\text{ °C}$
 (1) $\delta = 1$; DC
 (2) $\delta = 0.5$; $f = 20\text{ kHz}$
 (3) $\delta = 0.2$; $f = 20\text{ kHz}$
 (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig. 9. Average forward current as a function of solder point temperature; typical values

11. Test information

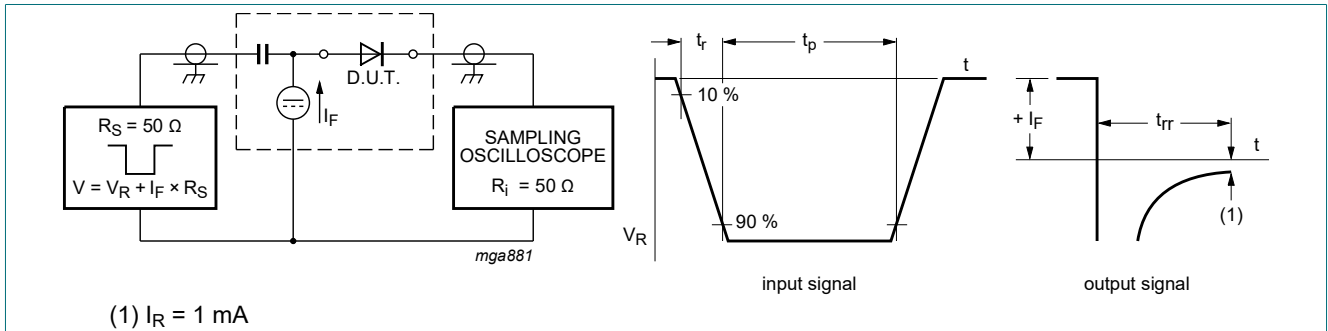


Fig. 10. Reverse recovery time: test circuit and waveforms

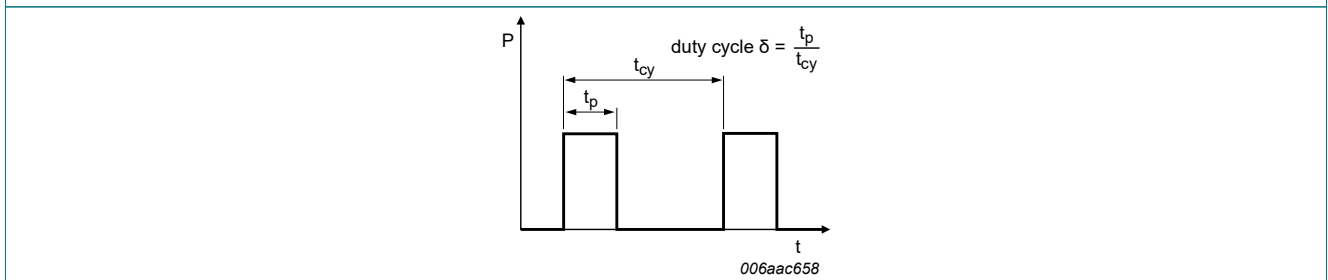


Fig. 11. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations: $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current, $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_M \times \sqrt{\delta}$ with I_{RMS} defined as RMS current.

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

12. Package outline

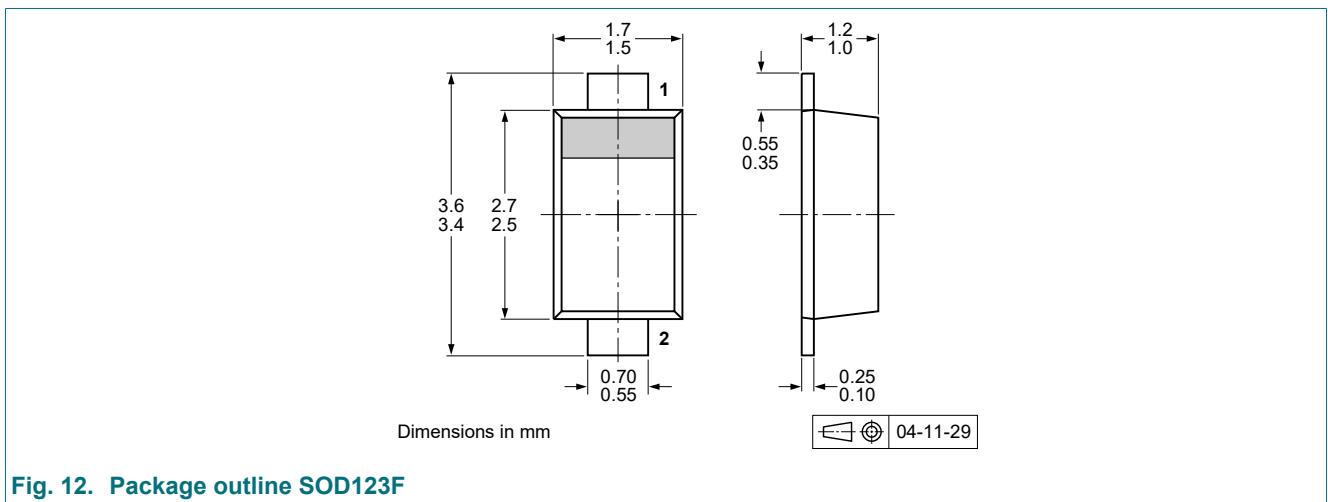


Fig. 12. Package outline SOD123F

13. Soldering

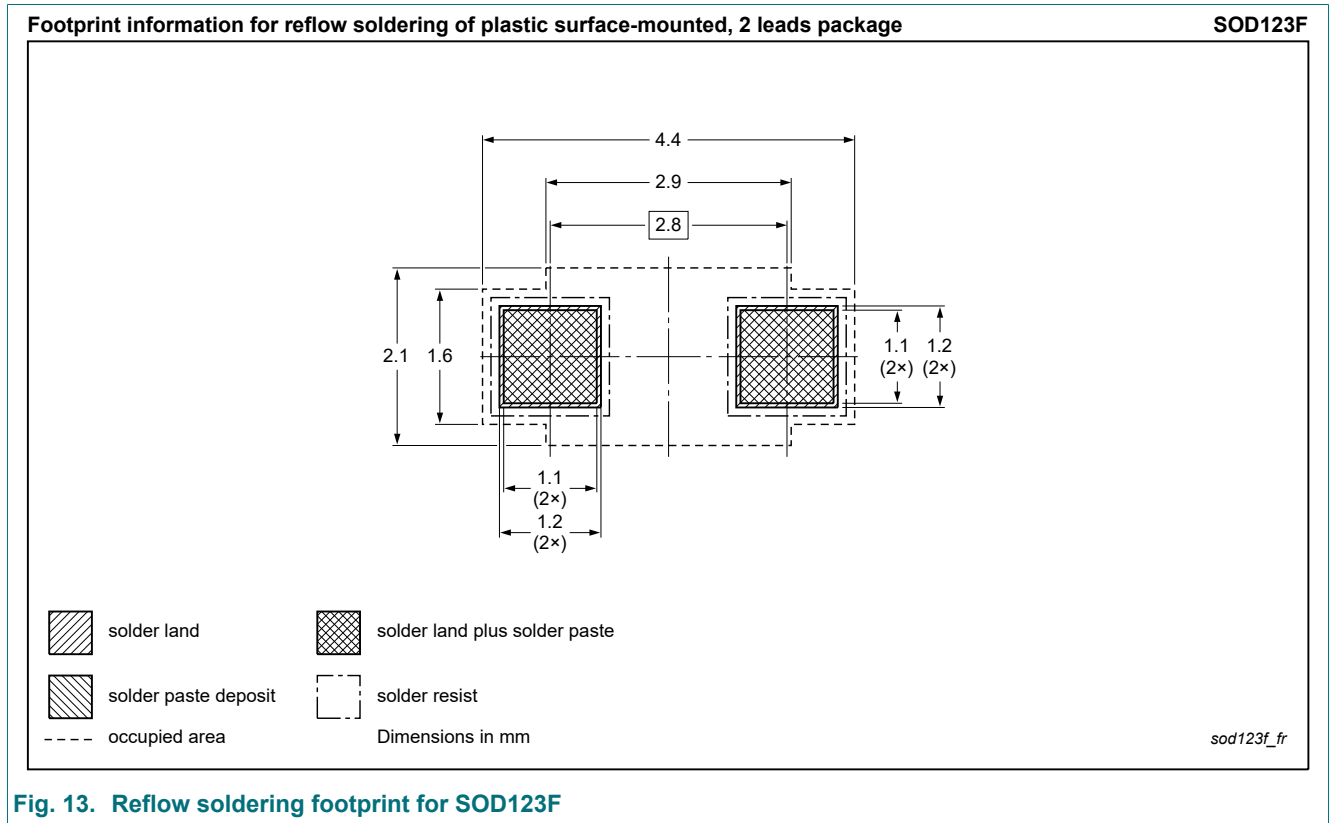


Fig. 13. Reflow soldering footprint for SOD123F

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
BAT46WH-Q v.1	20230320	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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